

Product Summary

Device	BV _{DSS}	Rds(on) max	Id max Ta = +25°C
Q1	20V	40mΩ @ VGS = 4.5V	4.7A
N-Channel	200	65mΩ @ Vgs = 2.5V	3.7A
Q2	-20V	90mΩ @ VGs = -4.5V	-3.2A
P-Channel	-200	137mΩ @ V _{GS} = -2.5V	-2.6A

Description

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

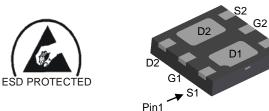
- Load Switch
- Power Management Functions
- Portable Power Adaptors

Features

- Low On-Resistance
- Low Input Capacitance
- Low Profile, 0.6mm Max Height
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please <u>contact us</u> or your local Diodes representative. <u>https://www.diodes.com/quality/product-definitions/</u>

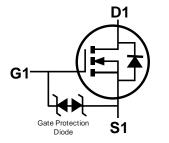
Mechanical Data

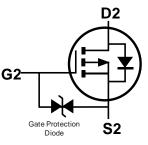
- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe; Solderable per MIL-STD-202, Method 208 @
- Terminal Connections: See Diagram Below
- Weight: 0.008 grams (Approximate)



Bottom View

U-DFN2020-6 (Type B)





Q1 N-CHANNEL MOSFET Q2 P-CHANNEL MOSFET Internal Schematic

Ordering Information (Note 4)

Part Number	Case	Packaging
DMC2041UFDB -7	U-DFN2020-6 (Type B)	3,000/Tape & Reel
DMC2041UFDB -13	U-DFN2020-6 (Type B)	10,000/Tape & Reel

Notes:

No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information

Site 1



D4 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: H = 2020) M = Month (ex: 9 = September)

Date Code Key

Year	2014		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	В		Н		J	K	L	М	N	0	Р	R
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec

Site 2



D4 = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 0 = 2020) W = Week (ex: a = Week 27; z Represents Week 52 and 53) X = Internal Code (ex: U = Monday)

Date Code Key

Year	2014	 2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	4	 0	1	2	3	4	5	6	7	8	9

Week	1-26	27-52	53
Code	A-Z	a-z	Z

Internal Code	Sun	Mon	Tue	Wed	Thu	Fri	Sat
Code	Т	U	V	W	Х	Y	Z



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Q1 N-CHANNEL	Q2 P-CHANNEL	Unit
Drain-Source Voltage			Vdss	20	-20	V
Gate-Source Voltage			Vgss	±12	±12	V
Continuous Drain Current (Note 5) N-Channel: V _{GS} = 4.5V	Steady State	T _A = +25°C T _A = +70°C	lo	4.7 3.8	-3.2 -2.5	А
P-Channel: $V_{GS} = 4.5V$	t < 5s	T _A = +25°C T _A = +70°C	ID	6.1 4.9	-4.1 -3.2	А
Maximum Continuous Body Diode Forward Current (Note 5)			ls	2	-1.5	А
Pulsed Drain Current (10µs Pulse, Duty Cycle =	: 1%)		I _{DM}	30	-18	А

Thermal Characteristics

Characteristic		Symbol	Value	Unit	
Total Power Dissipation (Note 5)	Steady State		1.4	W	
Total Power Dissipation (Note 5)	t < 5s	PD	2.2	vv	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State		92		
mermai Resistance, Junction to Ambient (Note 5)	t < 5s	$R_{ heta JA}$	55	°C/W	
Thermal Resistance, Junction to Case (Note 5)		Rejc	30		
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C	

Electrical Characteristics Q1 N-CHANNEL (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Мах	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)	Cymbol		176	Шах	onit	
Drain-Source Breakdown Voltage	BV _{DSS}	20		_	V	Vgs = 0V, ID = 250µA
Zero Gate Voltage Drain Current $T_J = +25^{\circ}C$	IDSS	_	_	1.0	μA	$V_{DS} = 20V, V_{GS} = 0V$
Gate-Source Leakage	lgss	_	_	±10	μA	$V_{GS} = \pm 8V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 6)	•					
Gate Threshold Voltage	V _{GS(TH)}	0.35	_	1.4	V	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$
Static Drain-Source On-Resistance		—	23	40		V _{GS} = 4.5V, I _D = 4.2A
Static Drain-Source On-Resistance	RDS(ON)	_	26	65	mΩ	$V_{GS} = 2.5V, I_D = 3.3A$
Diode Forward Voltage	V _{SD}	_	0.7	1.2	V	$V_{GS} = 0V, I_{S} = 4.4A$
DYNAMIC CHARACTERISTICS (Note 7)	·				•	÷
Input Capacitance	Ciss	—	713	_	pF	
Output Capacitance	Coss	—	80	—	pF	$V_{DS} = 10V, V_{GS} = 0V,$ - f = 1.0MHz
Reverse Transfer Capacitance	Crss	_	68	—	pF	1 - 1.00012
Gate Resistance	Rg	—	15	—	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$
Total Gate Charge (V _{GS} = 4.5V)	0	—	8	—	nC	
Total Gate Charge (V _{GS} = 8V)	Qg	_	15	—	nC	
Gate-Source Charge	Qgs	—	1.0	—	nC	$V_{DS} = 10V, I_D = 5.5A$
Gate-Drain Charge	Qgd	_	1.1	_	nC	
Turn-On Delay Time	tD(ON)	—	3.6	_	ns	
Turn-On Rise Time	tR		15.9	_	ns	V _{DD} = 10V, V _{GS} = 4.5V,
Turn-Off Delay Time	t _{D(OFF)}	—	16.0	_	ns	$R_L = 2.3\Omega, R_g = 1\Omega$
Turn-Off Fall Time	tF	_	2.6	_	ns	
Body Diode Reverse Recovery Time	t _{RR}	_	6.6	_	ns	I _S = 4.4A, dl/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q _{RR}	—	1.2	_	nC	I _S = 4.4A, dl/dt = 100A/µs

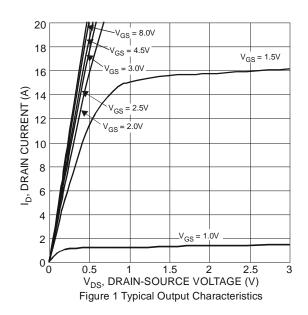
5. Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided. Notes: 6. Short duration pulse test used to minimize self-heating effect.
7. Guaranteed by design. Not subject to product testing.

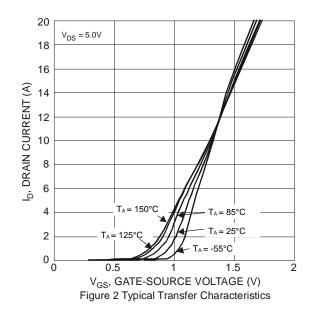


Electrical Characteristics Q2 P-CHANNEL (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)						
Drain-Source Breakdown Voltage	BVDSS	-20	—	_	V	$V_{GS} = 0V, I_{D} = -250 \mu A$
Zero Gate Voltage Drain Current $T_J = +25^{\circ}C$	IDSS	—	—	-1.0	μA	$V_{DS} = -20V, V_{GS} = 0V$
Gate-Source Leakage	lgss	—	—	±10	μA	$V_{GS} = \pm 8V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 6)						
Gate Threshold Voltage	VGS(TH)	-0.35	—	-1.4	V	$V_{DS} = V_{GS}$, $I_D = -250 \mu A$
Static Drain-Source On-Resistance	Provent	_	59	90	mΩ	VGS = -4.5V, ID = -2.9A
Static Drain-Source On-Resistance	Rds(on)	_	76	137	11152	V_{GS} = -2.5V, I_D = -2.3A
Diode Forward Voltage	Vsd	—	-0.65	-1.2	V	Vgs = 0V, Is = -3.0A
DYNAMIC CHARACTERISTICS (Note 7)						
Input Capacitance	Ciss	_	881	—	pF	
Output Capacitance	Coss	_	84	—	pF	└ V _{DS} = -10V, V _{GS} = 0V, - f = 1.0MHz
Reverse Transfer Capacitance	Crss	—	67	—	pF	
Gate Resistance	Rg	—	14.3	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$
Total Gate Charge (V _{GS} = -4.5V)	0	—	11	_	nC	
Total Gate Charge (V _{GS} = -8V)	Qg	_	18	_	nC	
Gate-Source Charge	Qgs	_	1.5	—	nC	$V_{DS} = -10V, I_D = -3.7A$
Gate-Drain Charge	Q _{gd}	_	2.3	—	nC	
Turn-On Delay Time	td(on)	_	5.0	_	ns	
Turn-On Rise Time	tR	_	9.5	_	ns	V _{DD} = -10V, V _{GS} = -4.5V,
Turn-Off Delay Time	tD(OFF)	_	29.7	—	ns	$R_L = 3.3\Omega, R_g = 1\Omega$
Turn-Off Fall Time	t⊨	_	20.4	—	ns	
Body Diode Reverse Recovery Time	t _{RR}		23.6	_	ns	Is = -3.0A, dl/dt = 100A/µs
Body Diode Reverse Recovery Charge	Q _{RR}		11.4	_	nC	Is = -3.0A, dl/dt = 100A/µs

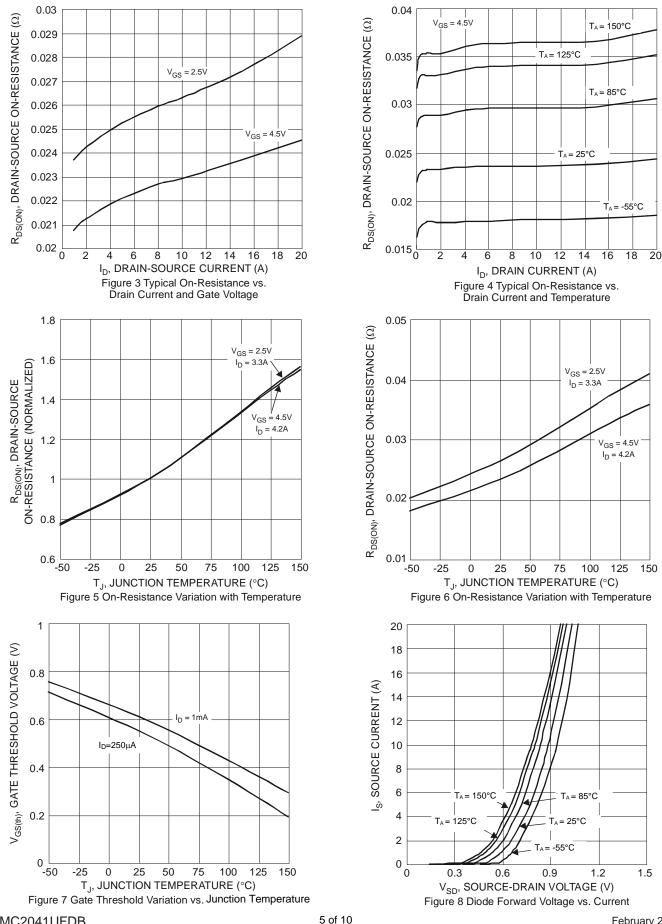
Notes: 6. Short duration pulse test used to minimize self-heating effect. 7. Guaranteed by design. Not subject to product testing.







DMC2041UFDB



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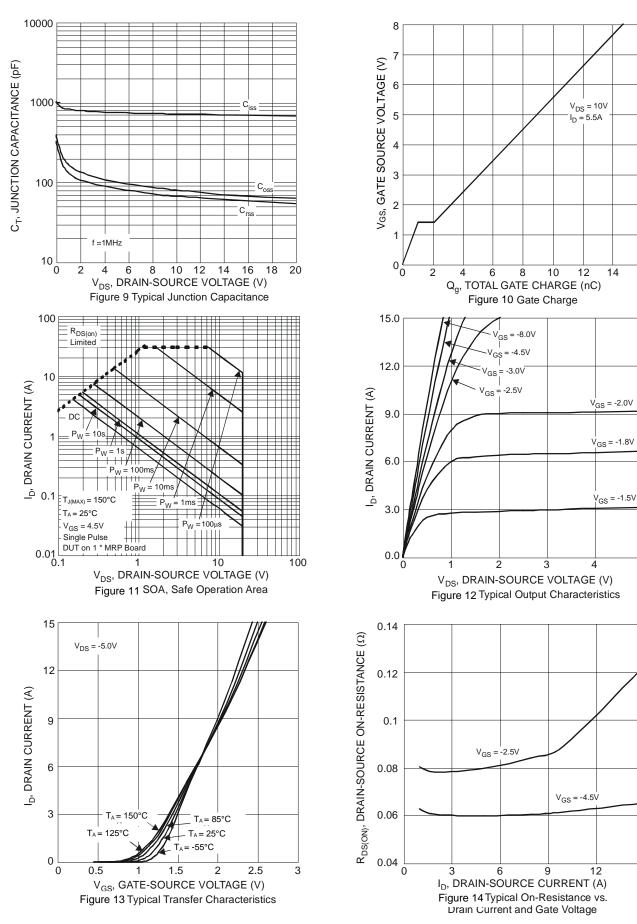
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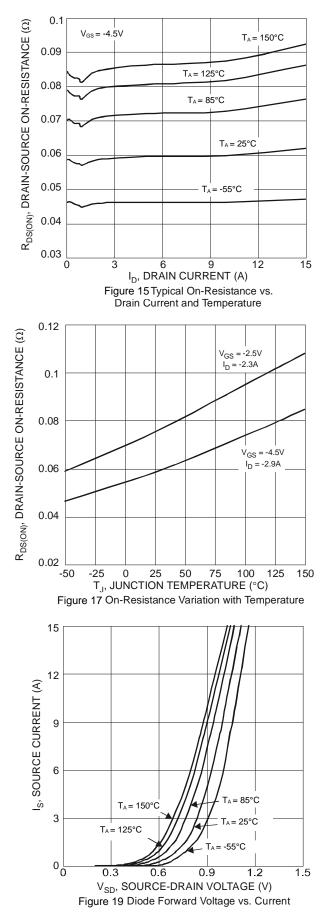
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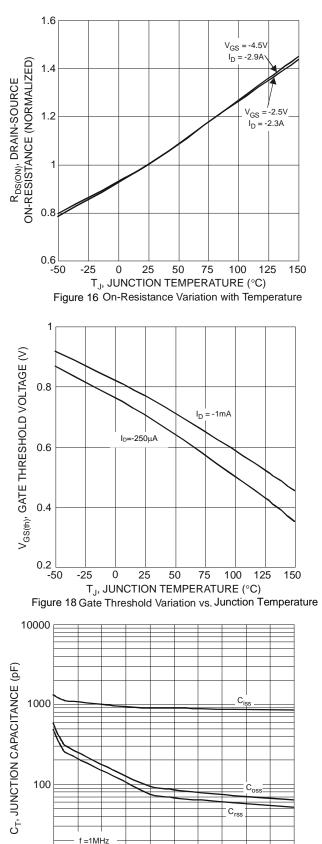


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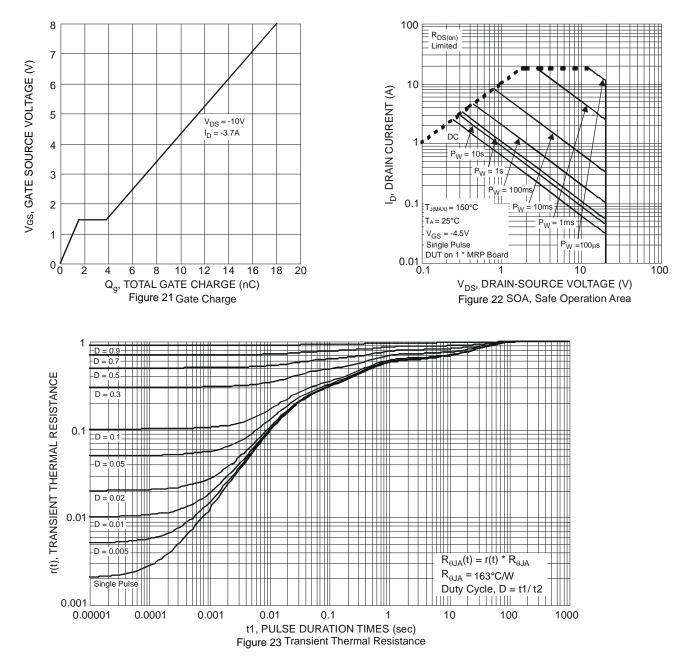




10 0 2 4 6 8 10 12 14 16 18 20 V_{DS}, DRAIN-SOURCE VOLTAGE (V) Figure 20 Typical Junction Capacitance



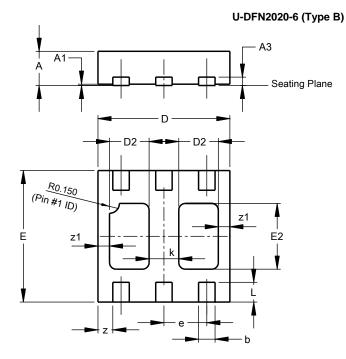
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Package Outline Dimensions

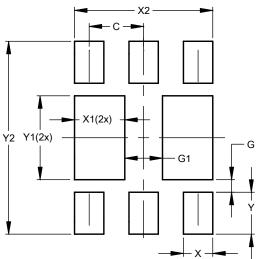
Please see http://www.diodes.com/package-outlines.html for the latest version.



		2020-6 e B	
Dim	Min	Max	Тур
Α	0.545	0.605	0.575
A1	0.00	0.05	0.02
A3	-	-	0.13
b	0.20	0.30	0.25
D	1.95	2.075	2.00
D2	0.50	0.70	0.60
е	-	-	0.65
E	1.95	2.075	2.00
E2	0.90	1.10	1.00
k	-	-	0.45
L	0.25	0.35	0.30
z	-	-	0.225
z1	-	-	0.175
All	Dimens	ions in	mm

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



U-DFN2020-6 (Type B)

Dimensions	Value			
Dimensions	(in mm)			
С	0.650			
G	0.150			
G1	0.450			
Х	0.350			
X1	0.600			
X2	1.650			
Y	0.500			
Y1	1.000			
Y2	2.300			



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